



## Material Content Data Sheet



<b>Sales Product Name</b>		BSP322P H6327		<b>Issued</b>		22. January 2018		
<b>MA#</b>		MA001623828						
<b>Package</b>		PG-SOT223-4-21		<b>Weight*</b>		113.65 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.074	0.06		648	
	non noble metal	tin	7440-31-5	0.019	0.02		167	
	inorganic material	silicon	7440-21-3	0.835	0.73	0.81	7344	8159
leadframe	inorganic material	silicon	7440-21-3	0.010	0.01		89	
	non noble metal	titanium	7440-32-6	0.051	0.04		446	
	non noble metal	chromium	7440-47-3	0.152	0.13		1338	
	non noble metal	copper	7440-50-8	50.489	44.43	44.61	444236	446109
wire	non noble metal	copper	7440-50-8	0.058	0.05	0.05	509	509
encapsulation	organic material	carbon black	1333-86-4	0.600	0.53		5278	
	plastics	epoxy resin	-	8.998	7.92		79174	
	inorganic material	silicondioxide	60676-86-0	50.391	44.34	52.79	443376	527828
leadfinish	non noble metal	tin	7440-31-5	1.464	1.29	1.29	12881	12881
plating	noble metal	silver	7440-22-4	0.513	0.45	0.45	4514	4514
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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